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INTERNATIONAL STANDARD



Semiconductor devices – Micro-electromechanical devices – Part 38: Test method for adhesion strength of metal powder paste in MEMS interconnection





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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

Part 38: Test method for adhesion strength of metal powder paste in MEMS interconnection

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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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